ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH LEADFRAME AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: forming a paddle having an indented planar surface intersecting an outwardly extending planar surface at an angle of approximately 135 degrees plus 25 degrees or minus 5 degrees; mounting an integrated circuit over the paddle; and forming an encapsulation over the integrated circuit and under the extension void free.

(Fig. 3)